Dear Sir / Madam,

I have been a professional in the manufacturing industry for over 30 years serving in various types of product manufacturing organizations. I have experience and expertise in leading high profile manufacturing engineering, project management, new product introduction and product change management teams. I worked in managerial positions for more than 10 years with multinational OEM and EMS companies thereby gaining extensive experience and deep competence in engineering management of complex network infrastructure product development, NPI and demand manufacturing.

I worked as Director for New Production Introduction operations for the last 2years in a multinational EMS company and was responsible to lead the team for new products to be manufactured for a highly renowned Network Product supplier, both Proto-type design as well as Pilot builds-start till First Customer Shipment launch and Mass-production.   
In the past I worked on a few new operation start-ups as well as new factory start-up from ground zero in Penang involving mainly in equipment, process, product, plant and quality engineering functions. I involve regularly with hands-on participation to motivate and align team players to be focused on achieving and exceeding set goals and customer satisfaction.

I have good management skills both in terms of leading a team and in any interface with the customer with strong testimony from customer of my accomplishments for my projects in my current organization for NPI programs. I am a reliable, loyal, strong team player, hard-working and fully committed person to meeting and exceeding customer expectations at all times.

Listed below are the different industries I have worked till now.

Semiconductor assembly & testing

Magnetic Head Slider manufacturing

Flexible Printed Circuit Board Manufacturing

PCBA and Box Build Manufacturing

My resume is as attached below.

Thanking you in advance

R Balakrishnan (R Bala)

Resume of Balakrishnan s/o Ramachandran

# **C:\Bala's photo.jpg**

# **Personal Particulars**

Name : Balakrishnan s/o Ramachandran

Sex : Male

Place of Birth: Georgetown, Penang, Malaysia

## Nationality: Malaysian

2X, Jalan Beriksa 2, Bandar Baru Air Itam,

Address: 11500 Air Itam, Penang, Malaysia

e-mail: bk\_rama57@yahoo.com

Tel Residence: +604 – 826 9230

Mobile Phone: +6012-5055594

#### **Relevant Skills /Knowledge / Capabilities**

New Product transfer and Project management

PCB Assembly and Electronics Assembly Engineering (Process / Equipment Maintenance / Product /Test)

(SMT/ AI / MI / Wave Soldering / Testing / Packaging / Product Assembly and some knowledge of COB)

Flexible Printed Circuit Board manufacturing

Slider Fabrication and Magnetic Head Assembly manufacturing process

Manufacturing Process Development and Quality Improvement

Positive Customer Interaction on DFM, RCA, FMA and SCAR

Interpretation of Electrical/Electronics and Mechanical Drawings

Product, Process and Piece Parts Qualification

Conduct Manufacturing, Quality, Process Characterization and Lead-Free capability assessment review / auditing

QS 9000 Elements, ISO 19000 / 14000 Elements, IPC 610D

**Working Experience:**

**Present:**

**Position:** **New Product Introduction (NPI) Director**

**Company**: Flextronics Technology Sdn Bhd

Bukit Minyak

Perai

Penang, Malaysia

**Working Period :** February 2012 till now

**Job Description:** Lead the New Product Introduction team comprising of Technical Program Managers while working with cross-functional team of Product Engineers, Process Engineers, Equipment Engineers, Test Engineers, Production Leads and Material/Commodity Analyst to support new product builds, both transfers as well as from proto stage. Also lead the Manufacturer Change Notification execution team comprising of Program Administrators and Process Engineers for the same business account. Emphasize on early engagement with customer team for all level of builds so as to provide DFM feedback as well as process / product development support to customer, manufacturing cost quotes, NRE quotes and ensure the start-up is done correctly and effectively. Ensure team meets the build schedules and achieve the required FPY / ETE targets defined by customer to meet First Customer Shipment target dateline.

Accomplishments: a) Successfully completed a new Network product launch to meet the Pilot build and First Customer Ship launch as planned by the customer - NPI stage till mass production. Provided the first point of escalation support to customer and lead the weekly meetings as well as being main point of customer contact for feedback and updates.

Provided leadership for internal team to improve customer satisfaction and developed the confidence among customer Program managers and BU Leads (5 BUs) on Flex NPI performance related to commitment, execution and delivery. Structured the NPI team’s TPM support for other customer BU programs to work closely with their PMs to successfully execute and complete all NPI related builds for most of the programs and transition to mass production build.

b) Restructured the Manufacturer Change Notification executing organization to provide focused attention to the different customer BU (8 BUs) program managers and product engineers as well as to clear all backlog cases for component qualification that was aging more than 100days. Customer satisfied with the team performance and commitment. Provided the first point of escalation support to customer and participate in meetings.

**Previous Employment:**

**Position:** **Product Change Manager &**

**Engineering Lead – Product and Supplier Base Engineering**

**Company**: Alcatel-Lucent Malaysia Sdn Bhd

20th Floor, Sunrise Tower

No.86, Jalan Ampang

50450 Kuala Lumpur

Malaysia

+603 2050 4138

**Working Period :** September 2006 till February 2012

**Job Description: Product Change Manager:** Propose a detailed Change Notice (CN) implementation plan and gain approval from the Business Unit (BU) for deployment. Has overall project responsibility for deployment and schedule completions. Interface with Program Management, Installation, Business Unit representatives and the customer to determine project priorities for deployment and scheduling compliance. Chair Project implementation meetings with appropriate personnel. Escalate critical issues to senior management when necessary. Prepare detailed reports on project performance and schedules as directed. Ensure all project plans are complete and maintain related data base.

**Lead Sr Engineer**: Lead an on-site team of Senior Product and Test engineers to oversee the performance of Alcatel-Lucent IP product manufacturing EMS located in Penang Malaysia and APAC region for yield and quality. The sectors supported are Material, Planning, Manufacturing, Quality, Delivery and RMA on a real time basis for all products. Coordination and execution of the NPI transfer activities till mass production release. First in line to interface with suppliers for FMA and RCA on product quality issues reported by customer and ensure corrective actions are effectively implemented.

**Role / Responsibilities:** Provide technical support and guidance related to the manufacturing process and quality expectations of Alcatel-Lucent products being manufactured at the EMS. Lead the RCA, FMA and SCAR response investigation / analysis activity at the EMS site for timely and effective closure.

Conduct Manufacturing Process and Quality Audits at various ALU supplier sites in APAC region to characterize their process and improve manufacturing capability.

Lead-Free Qualification - coordinate and conduct Lead-Free capability assessment and readiness audit at ALU supplier sites in APAC region.

Provide feedback to product development engineering on requirements to enhance manufacturability of product both existing and NPI

Co-ordinate and participate in internal quality review meeting with supplier, Alcatel-Lucent Quality Work Group and Customer Quality Group.

**Achievements:** Managed the local engineering team to be independent whilst effectively meeting the goals and objectives set by ALU management at all times.

Ensure that the manufacturing supplier performance / quality indicators consistently meet or exceed the target set. Conduct periodic roving audit and line performance review with EMS team.

Work with EMS engineers to address out-of-control situations and unique issues impacting in-process quality thereby defining solutions for permanent fix.

Provided on-site technical guidance for supplier (OEM in Taiwan) to root-cause a repeated product quality issue related to crack under BGA pad whilst confirming it’s not contributed by any manufacturing process

Successful completion of product manufacturing / quality audits (Lead and Lead-Free) at various EMS / OEM supplier sites in China, Thailand, Philippine and Taiwan providing suggestion / recommendations for further improvement. Share the best know practices in the industry with suppliers for process and product quality enhancement.

Provide FMA and RCA feedback on customer reported field failures for acceptance and effective closure.

**Position:**  **Project Manager (Nov-2005 - Sep2006)**

**Asst. Manufacturing Engineering Manager (July ‘05) / Sr. Project Engineer (April’02 – June’05)**

**Company**: Jabil

Phase 4, 1100 Penang, Malaysia

**Responsibilities**: 1) Lead a team of Manufacturing Engineers (4) and Technicians (6) in Manufacturing Engineering Team to meet and exceed set manufacturing goals on Quality, Cost and Delivery within the Workcell.

2) Manage the New Products Transfer, Introduction and Start-up activities as well as prepare product manufacturing costing, capacity and manpower analysis

3) Provide training, guidance and technical assistance to process engineers and technicians as and when required for better understanding of process as well as to have the right fix to a problem. Process development and enhancement actions to improve quality, cost and productivity

4) Interaction with customer on product and process quality performance indicators as well as improvement plans to enhance product assembly process.

5) Perform piece part assembly specification review and qualification support for Vendor sample qualification activities. Cost reduction activities in the form of process improvement, localization

and standardization.

**Achievements:** 1) Plan, execute, commission and complete transfer of NOKIA project from Jabil Mexico to Jabil Penang between November 2005 - April 2006

2) Personal hands on involvement in the transfer and start-up activities to ensure effective and timely execution of project to meet customer ship dates .Successfully planned and transferred 4 Platform of products with PCBA and some Box Build processes from the US.

3) Perform NPI build execution and subsequent mass production run successfully thereby attaining targeted yields set by customer.

4) Work closely with the manufacturing engineers and quality engineers to implement process improvement activities to enhance productivity and quality .This results in reducing cost of quality.

5) Work on DFM ideas and concepts for product quality and productivity improvement which are accepted by customer for implementation on most cases.

Provide cost estimates for RFQ and product rework or upgrade requirements.

6) Have had good and effective communication with customer and attained good ratings in CSI

**Position: Engineering Manager**

**Company**: COB Technology Asia Sdn. Bhd.

Sungai Petani , Kedah,Malaysia

**Nature of Business:** PCB Assembly/ Chip On Board Contract Manufacturing

**Responsibilities**: 1) Manage a team of Engineers and Technicians in Process, Product, Equipment and Test Engineering to meet and exceed set goals.

2) Manage the NPI transfer and manufacturing process / test operation.

3) Process development and enhancement to improve quality, cost and

poductivity.

.

**Achievements:** 1) Implement periodic maintenance of part feeders for SMT machines to reduce attrition from 0.8 % to 0.3 % against a target of 0.25 %

2) Reduced the turn around time for debug WIP clearance from 6 days to 3 days as required by management via improving the process yields and also close loop feedback between test and process/product engineers .Also implemented a debug WIP daily clearance target.

3) Process defects related to wrong orientation , wrong components (IC) being mounted were eliminated by using detailed Visual Aids and Inspection Templates as well as implementing a First Board buy-off procedure.

4) Test fixture maintenance was enhanced to reduce NPF from 15% to 5%.

5) Implemented the ‘cell’ manufacturing concept for customer focused team

.

**Position** **Engineering Manager**

**Company**: Sanmatech Sdn. Bhd.

Penang, Malaysia

(PCBA manufacturing)

**Position**  **Assistant Manager Process Engineering**

**Company**: Solectron Technology Sdn. Bhd.

Prai Industrial Estate,

Penang, Malaysia

**Position**  **Engineering Manager** (Process /Equipment and AMT)

**Company:** QDOS Microcircuit Sdn. Bhd.

Kulim, Kedah, Malaysia

**Business:** Flexible Printed Circuit Board manufacturing

**Position : Section Head Engineering**

Dastek Asia Sdn Bhd

Magnetic Head Manufacturing

**Position 7: Engineer**

**Company** Applied Magnetics Sdn Bhd

Magnetic Head Manufacturing

#### **Education**

**Attained:** Diploma in Electrical / Electronic Engineering

Federal Institute of Technology

Kuala Lumpur

Graduation: April 1978

City & Guilds of London in Electrical Engineering Practice

**Reference:**

Robert Sawyer Elanggovan Ramasamy Paul Bailey

Senior Director NPI Senior Director Engineering Director Program Management

Flextronics Penang (P2) Flextronics Penang Flextronics Austin

Bukit Minyak Bukit Minyak Texas USA

Prai, Penang Prai, Penang Off Tel: 512-4257276

Tel: 6 010 4078301 Tel: 6 012 4806506 Mob#: 512-9178055

Robert.Sawyer@flextronics.com ElanggovanAl.Ramasamy@flextronics.com Paul.Bailey@flextronics.com